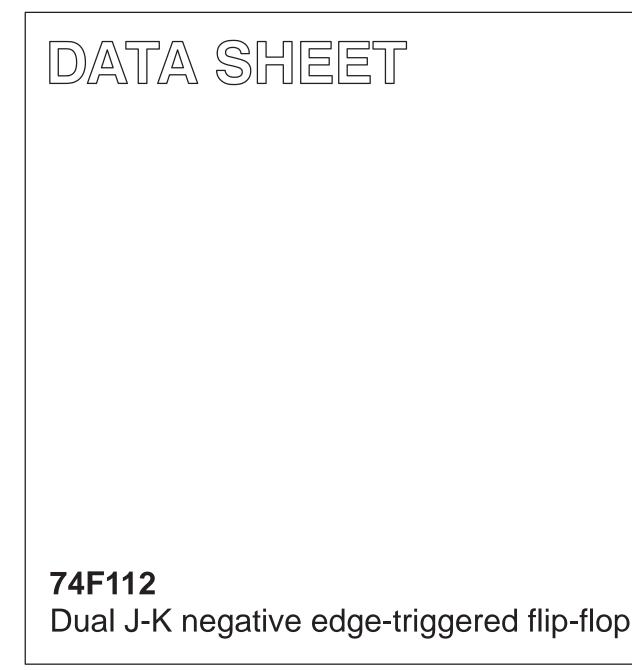
INTEGRATED CIRCUITS



Product specification

1990 Feb 09

IC15 Data Handbook



HILIP

Philips Semiconductors

74F112

FEATURE

Industrial temperature range available (-40°C to +85°C)

DESCRIPTION

The 74F112, Dual Negative Edge-Triggered JK-Type Flip-Flop, feature individual J, K, Clock (\overline{CPn}), Set (\overline{SD}) and Reset (\overline{RD}) inputs, true (Qn) and complementary (\overline{Qn}) outputs.

The \overline{SD} and \overline{RD} inputs, when Low, set or reset the outputs as shown in the Function Table, regardless of the level at the other inputs.

A High level on the clock (\overline{CPn}) input enables the J and K inputs and data will be accepted. The logic levels at the J and K inputs may be allowed to change while the \overline{CPn} is High and flip-flop will perform according to the Function Table as long as minimum setup and hold times are observed. Output changes are initiated by the High-to-Low transition of the \overline{CPn} .

PIN CONFIGURATIO	N	
CP0 [1 K0 [2 J0 [3 SD0 [4 Q0 [5 Q0 [6 Q1 [7	16 Vcc 15 RD 14 RD 13 CP 12 K1 11 J1 10 SD) 1
GND 8	9 Q1	
	SF00103	

ТҮРЕ	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F112	100MHz	15mA

ORDERING INFORMATION

	(DRDER CODE	
DESCRIPTION	COMMERCIAL RANGE V _{CC} = 5V \pm 10%, T _{amb} = 0°C to +70°C	INDUSTRIAL RANGE V_{CC} = 5V ±10%, T_{amb} = -40°C to +85°C	PKG DWG #
16-pin plastic DIP	N74F112N	I74F112N	SOT38-4
16-pin plastic SO	N74F112D	I74F112D	SOT109-1

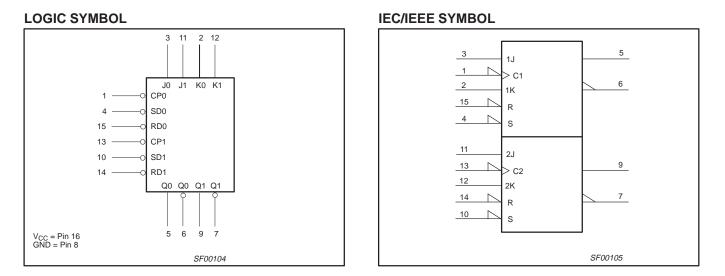
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
J0, J1	J inputs	1.0/1.0	20µA/0.6mA
K0, K1	K inputs	1.0/1.0	20µA/0.6mA
SD0, SD1	Set inputs (active Low)	1.0/5.0	20µA/3.0mA
RD0, RD1	Reset inputs (active Low)	1.0/5.0	20µA/3.0mA
<u>CP</u> 0, <u>CP</u> 1	Clock Pulse input (active falling edge)	1.0/4.0	20µA/2.4mA
Q0, Q0; Q1, Q1	Data outputs	50/33	1.0mA/20mA

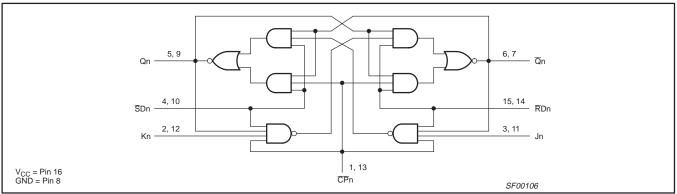
NOTE:

One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

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LOGIC DIAGRAM



FUNCTION TABLE

		INPUTS			Ουτι	PUTS	OPERATING MODE
SD	RD	СР	J	К	Q	Q	OFERATING MODE
L	Н	Х	Х	Х	Н	L	Asynchronous Set
Н	L	Х	Х	Х	L	Н	Asynchronous Reset
L	L	Х	Х	Х	H*	H*	Undetermined *
Н	Н	\downarrow	h	h	q	q	Toggle
Н	Н	\downarrow	I	h	L	Н	Load "0" (Reset)
Н	Н	\downarrow	h	I	Н	L	Load "1" (Set)
Н	Н	\downarrow	I	I	q	q	Hold "no change"
Н	Н	Н	Х	Х	Q	Q	Hold "no change"

H = High voltage level

h = High voltage level one setup time prior to High-to-Low clock transition

L = Low voltage level

I = Low voltage level one setup time prior to High-to-Low clock transition

q = Lower case letters indicate the state of the reference output prior to the High-to-Low clock transition

 \dot{X} = Don't care

 \downarrow = High-to-Low clock transition

* = Both outputs will be High while both SD and RD are Low, but the output states are unpredictable if SD and RD go High simultaneously.

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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current		-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state		–0.5 to V_{CC}	V
I _{OUT}	Current applied to output in Low output state		40	mA
-		Commercial range	0 to +70	°C
lamb	Operating free-air temperature range	Industrial range	-40 to +85	°C
T _{stg}	Storage temperature range	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			LIMITS		UNIT
STWBOL	PARAMETER	MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	High-level input voltage		2.0			V
V _{IL}	Low-level input voltage				0.8	V
I _{IK}	Input clamp current				-18	mA
I _{OH}	High-level output current				-1	mA
I _{OL}	Low-level output current				20	mA
-		Commercial range	0		+70	°C
T _{amb}	Operating free-air temperature range	Industrial range	-40		+85	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

				201		LIMITS		
SYMBOL	PARAMETER	TEST CONDITIC	JNS'	MIN	TYP ²	MAX	UNIT	
Varia	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}	2.5			V
V _{OH}	High-level output voltage		$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		v
V			$V_{CC} = MIN, V_{IL} = MAX$	$\pm 10\% V_{CC}$		0.35	0.50	V
V _{OL}	Low-level output voltage		$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.35	0.50	v
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V
l _l	Input current at maximum input	voltage	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current	-	$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
		Jn, Kn					-0.6	mA
IIL	Low-level input current	CPn	$V_{CC} = MAX, V_I = 0.5V$				-2.4	mA
	SDn, RDn						-3.0	mA
I _{OS}	Short-circuit output current ³		V _{CC} = MAX		-60		-150	mA
I _{CC}	Supply current (total) ⁴	Supply current (total) ⁴				15	21	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. 3. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

4. Measure I_{CC} with the clock input grounded and all outputs open, with the Q and \overline{Q} outputs High in turn.

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AC ELECTRICAL CHARACTERISTICS

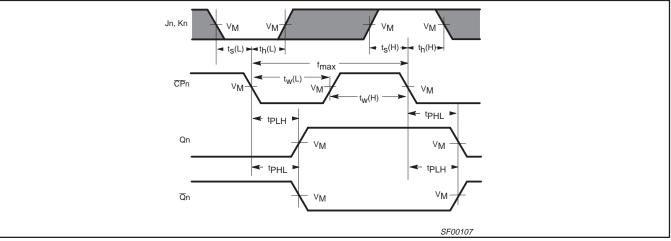
						LI	MITS					
SYMBOL	PARAMETER	TEST CONDITION	C	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_L = 50pF$ $R_L = 500\Omega$		C _L = 50pF		V _{CC} = +5. T _{amb} = 0°C C _L = R _L =	50pF	$V_{CC} = +5.$ $T_{amb} = -40^{\circ}$ $C_{L} = 0^{\circ}$ $R_{L} = 0^{\circ}$	°C to +85°C 50pF	UNIT
			MIN	ТҮР	MAX	MIN	MAX	MIN	MAX			
f _{MAX}	Maximum clock frequency	Waveform 1	85	100		80		80		MHz		
t _{PLH} t _{PHL}	Propagation delay \overline{CP} to Qn or $\overline{Q}n$	Waveform 1	2.0 2.0	5.0 5.0	6.5 6.5	2.0 2.0	7.5 7.5	2.0 2.0	7.5 7.5	ns		
t _{PLH} t _{PHL}	Propagation delay SDn, RD to Qn or Qn	Waveform 2,3	2.0 2.0	4.5 4.5	6.5 6.5	2.0 2.0	7.5 7.5	1.5 1.5	7.5 7.5	ns		

AC SETUP REQUIREMENTS

						LI	MITS					
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF$ $R_{L} = 500\Omega$		T _{amb} = +25°C C _L = 50pF		T _{amb} = +25°C C _L = 50pF		0V ± 10% C to +70°C 50pF 500Ω	$V_{CC} = +5.$ $T_{amb} = -40^{\circ}$ $C_{L} = 0^{\circ}$ $R_{L} = 0^{\circ}$	°C to +85°C 50pF	UNIT
			MIN	TYP	MAX	MIN	МАХ	MIN	MAX			
t _S (H) t _S ((L)	Setup time, High or Low Jn, Kn to CP	Waveform 1	4.0 3.5			5.0 4.0		5.0 4.0		ns		
t _h (H) t _h (L)	Hold time, High or Low Jn, Kn to CP	Waveform 1	0.0 0.0			0.0 0.0		0.0 0.0		ns		
t _W (H) t _W (L)	CP Pulse width High or Low	Waveform 1	4.5 4.5			5.0 5.0		5.0 5.0		ns		
t _W (L)	SDn, RD Pulse width Low	Waveform 2,3	4.5			5.0		5.0		ns		
t _{REC}	Recovery time SDn, RD to CP	Waveform 2,3	4.5			5.0		5.0		ns		

AC WAVEFORMS

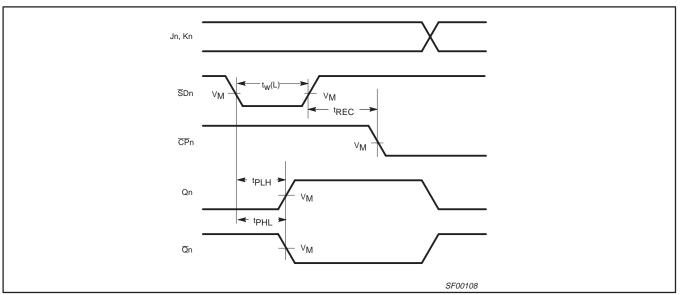
For all waveforms, $V_M = 1.5V$.



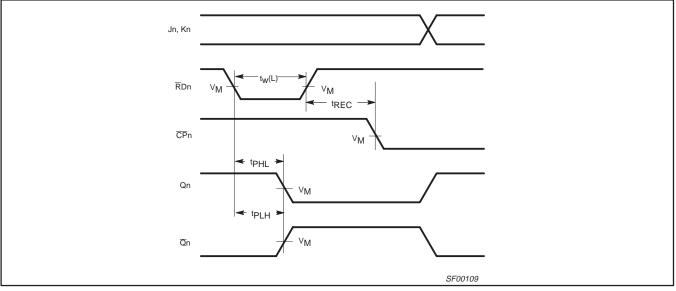
The shaded areas indicate when the input is permitted to change for predictable output performance.

Waveform 1. Propagation Delay for Data to Output, Data Setup Time and Hold Times, and Clock Pulse Width

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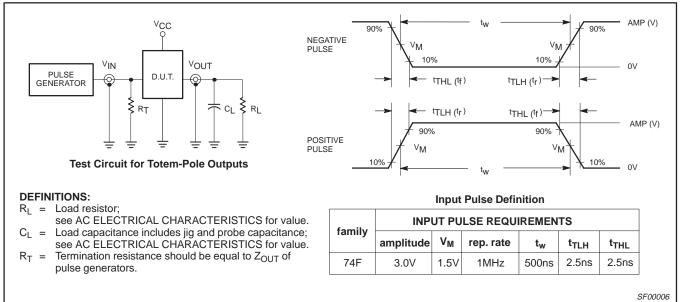
Waveform 2. Propagation Delay for Set to Output, Set Pulse Width, and Recovery Time for Set to Clock

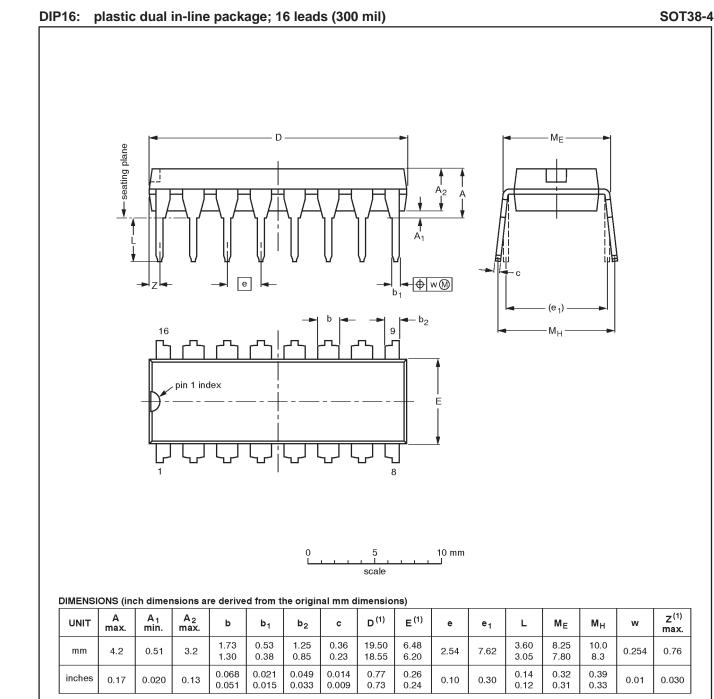


Waveform 3. Propagation Delay for Reset to Output, Reset Pulse Width, and Recovery Time for Reset to Clock

74F112

TEST CIRCUIT AND WAVEFORMS







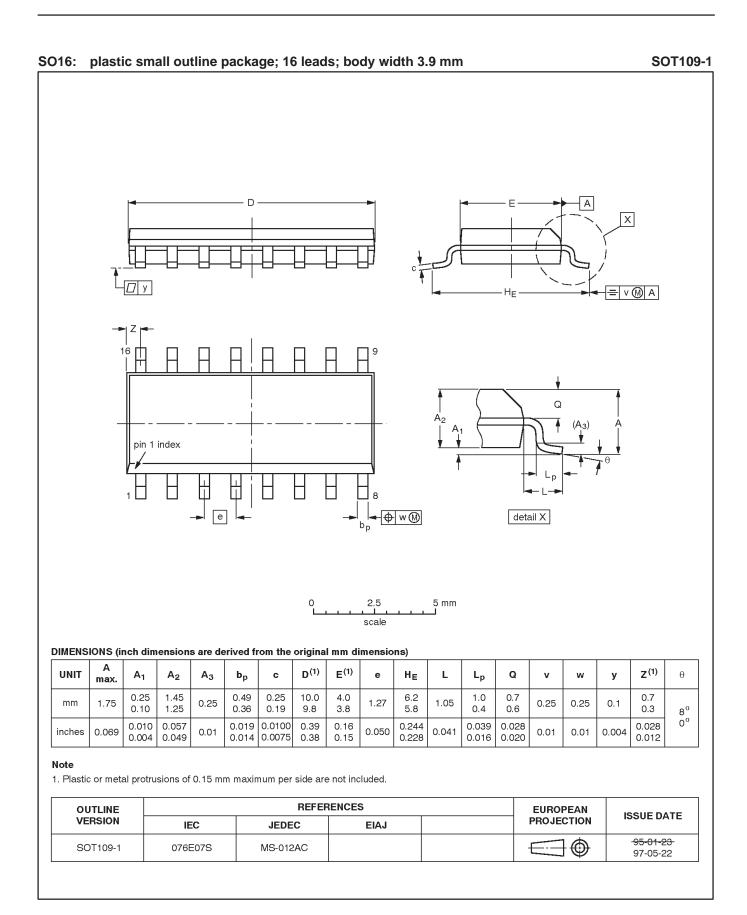
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4					\bigcirc	-92-11-17 95-01-14

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Philips Semiconductors

Dual J-K negative edge-triggered flip-flop



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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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